OPTO-ELECTRONIC MODULE AND METHOD FOR MANUFACTURING THE SAME

Abstract

A method for manufacturing a device (1) is suggested. The device comprises at least one opto-electronic modul (1), and the method comprises creating a wafer stack (2) comprising a substrate wafer (PW), and an optics wafer (OW); wherein a multitude of active optical components (E) is mounted on the substrate wafer (PW), and the optics wafer (OW) comprises a multitude of passive optical components (L). Each of the opto-electronic modules (1) comprises at least one of the active optical components (E) and at least one of the passive optical components (L). The optics wafer (OW) can comprise at least one portion, referred to as blocking portion, which is at least substantially non-transparent for at least a specific wavelength range, and at least one other portion, referred to as transparent portion, which is at least substantially non-transparent for at least said specific wavelength range. 11.The opto-electronic module comprises a substrate member; an optics member; at least one active optical component mounted on said subtrate member; and at least one passive optical component comprised in said optics member. The optics member (OW) is directly or indirectly fixed to said substrate member (PW). The opto-electronic modules (1) can have an excellent manufacturability while being small in dimension and having a high alignment accuracy.

[Fig. 11]